

In the Claims:

Claims 1-13. (Cancelled)

14. (New) A semiconductor package, comprising:

a leadframe comprising a plurality of leads segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed relation to a respective one of the leads of the remaining set, each of the leads defining opposed, generally planar top and bottom sides;

a semiconductor chip partially overlapping and attached to the top side of at least one of the leads of each of the sets, the semiconductor chip being electrically connected to at least one of the leads; and

a sealing material at least partially encapsulating the leadframe and the semiconductor chip such that the bottom side of each of the leads is exposed within the sealing material.

15. (New) The semiconductor package of Claim 14 wherein:

each of the leads further defines an inner end and a notched surface which is disposed in opposed relation to the bottom side and extends to the inner end;

each of the leads has a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface; and

the semiconductor chip partially overlaps and is attached to the notched surface of at least one of the leads of each of the sets.

16. (New) The semiconductor package of Claim 15 wherein the semiconductor chip is electrically connected to the top side of at least one of the leads via a conductive wire which is covered by the sealing material.

17. (New) The semiconductor package of Claim 15 wherein the semiconductor chip is electrically connected to the notched surface of at least one of the leads via a solder ball which is covered by the sealing material.

18. (New) The semiconductor package of Claim 15 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

19. (New) The semiconductor package of Claim 14 wherein:

each of the leads further defines an inner end and a notched surface which is disposed in opposed relation to the top side and extends to the inner end; and

each of the leads has a first thickness between the top and bottom sides which exceeds a second thickness between the top side and the notched surface.

20. (New) The semiconductor package of Claim 19 wherein the semiconductor chip is electrically connected to the top side of at least one of the leads via a conductive wire which is covered by the sealing material.

21. (New) The semiconductor package of Claim 14 wherein:

each of the leads further defines an outer end; and

the sealing material encapsulates the leadframe such that the outer end of each of the leads is exposed within the sealing material.

22. (New) The semiconductor package of Claim 14 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

23. (New) The semiconductor package of Claim 14 wherein the top sides of the leads extend in generally co-planar relation to each other.

24. (New) A leadframe comprising:

a peripheral tie bar; and

a plurality of leads connected to the tie bar and segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed relation to a respective one of the leads of the remaining set, each of the leads defining:

opposed, generally planar top and bottom sides;

an inner end; and

a notched surface which is disposed in opposed relation to the bottom side and extends to the inner end;

each of the leads having a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface.

25. (New) The leadframe of Claim 24 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

26. (New) The leadframe of Claim 24 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

27. (New) The leadframe of Claim 24 wherein the top sides of the leads extend in generally co-planar relation to each other.

28. (New) A leadframe comprising:

a peripheral tie bar; and

a plurality of leads connected to the tie bar and segregated into two sets, the leads of each set being linearly aligned and arranged in spaced, generally parallel relation to each other such that each of the leads of one set extends in opposed

relation to a respective one of the leads of the remaining set, each of the leads defining:

opposed, generally planar top and bottom sides;

an inner end; and

a notched surface which is disposed in opposed relation to the top side and extends to the inner end;

each of the leads having a first thickness between the top and bottom sides which exceeds a second thickness between the bottom side and the notched surface.

29. (New) The leadframe of Claim 28 wherein the notched surfaces of the leads extend in generally co-planar relation to each other.

30. (New) The leadframe of Claim 28 wherein the bottom sides of the leads extend in generally co-planar relation to each other.

31. (New) The leadframe of Claim 28 wherein the top sides of the leads extend in generally co-planar relation to each other.